	产	品规	配格承	シ	(书		
	SP	ECIF	FICAT		ONS		
客户: CUSTOMI	ER:						
客户型	PTION: 弓:		gnetic .				
产品型	ER PART NO: 号: DEL NO:						
	 字,盖章后请返 RETURN TO US			ECIF	ICATION	FOR APPROVA	L"
WITH YO	OUR APPROVED	SIGNATUR	ES				
Approve	ed LiuFei	Audit	LiuFei		Making	LiuXiaoMei	
Custon	er Acknowle	dges Sig	nature				
	Date						
	$NGLES = \pm HOLEDIA = \pm$			NGS AN	ND SPECIFICATI	e ShenZhen Technolo	TY OF PBXY
DRAWN BY : Sera DESIGNED BY: Sera	CHECKED E APPROVED			OR TH	IE MANUFACTU	NOT BE REPRODUCED RE OR SALE OF APP	
TITLE: CHIP2450-1	LE: CHIP2450-1608 Specification		DOCUMEN NO.	Т	1	608	SPEC REV. P1

PBX1608MA01 Specification

Operating Temp. : $-40^{\circ}C \sim +85^{\circ}C$

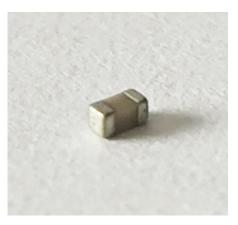
1. FEATURES:

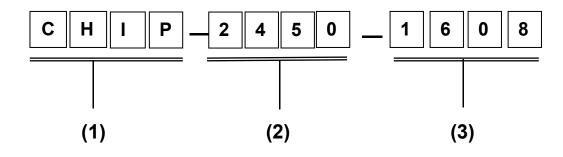
- Light weight, compact
- Wide bandwidth, low cost
- Built-in antenna with high gain

2. APPLICATIONS:

- Bluetooth, Wireless LAN, Mobile TV
- Home RF System, etc

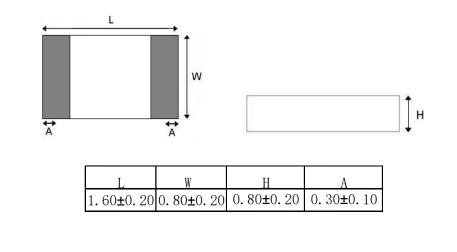




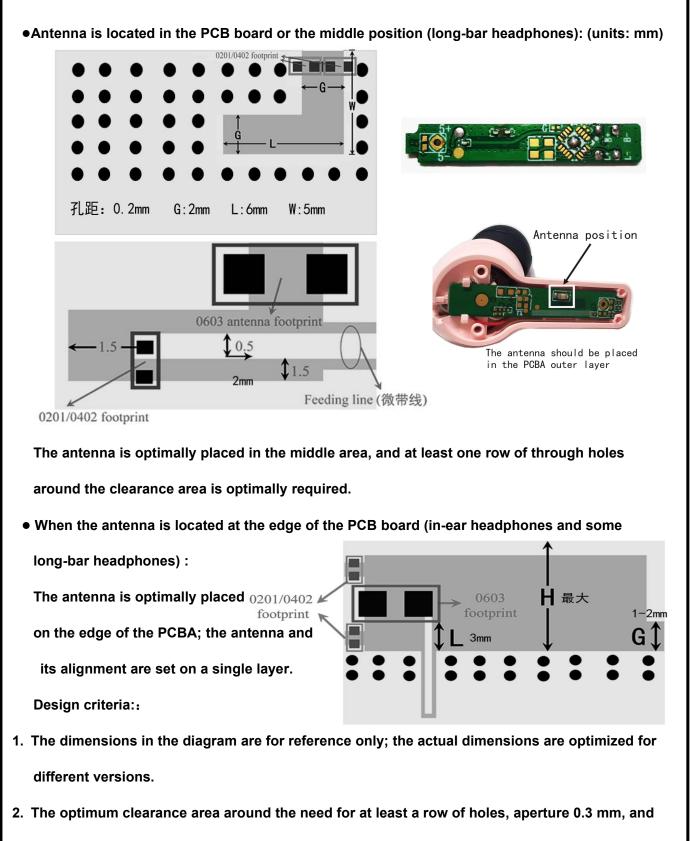


- (1) Product type: Multilayer chip Antenna
- (2) Center Frequency: 2450MHz
- (3) External Dimensions (L×W) (mm): 1.6*0.8

4. SHAPE AND DIMENSIONS:

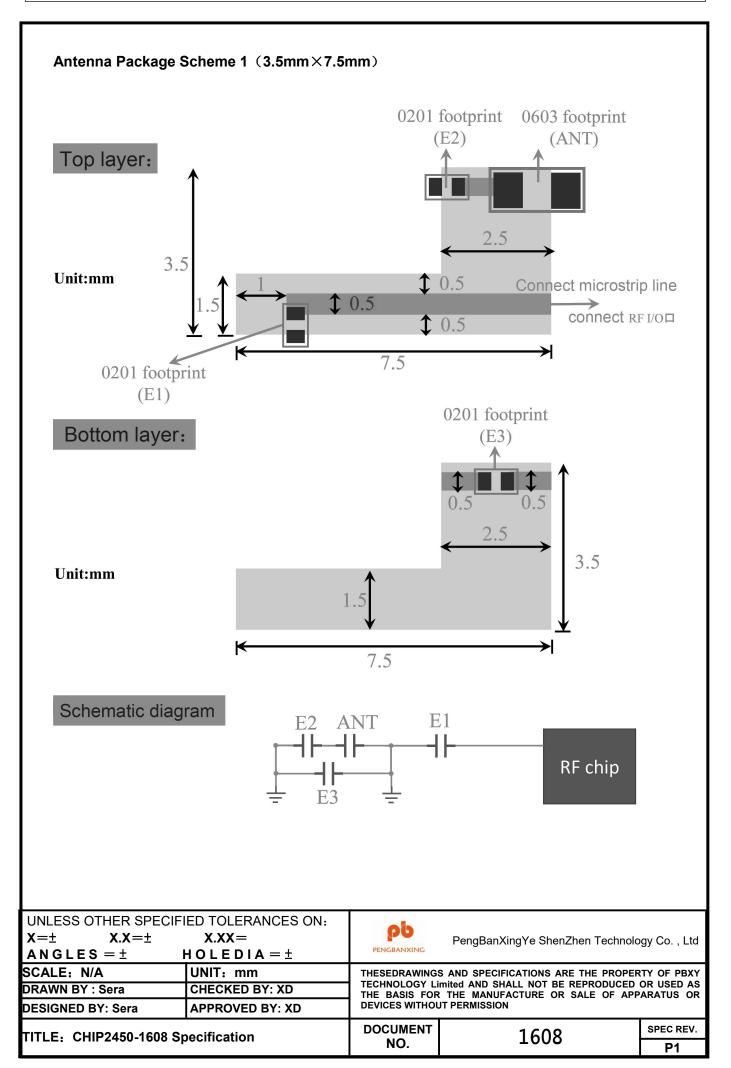


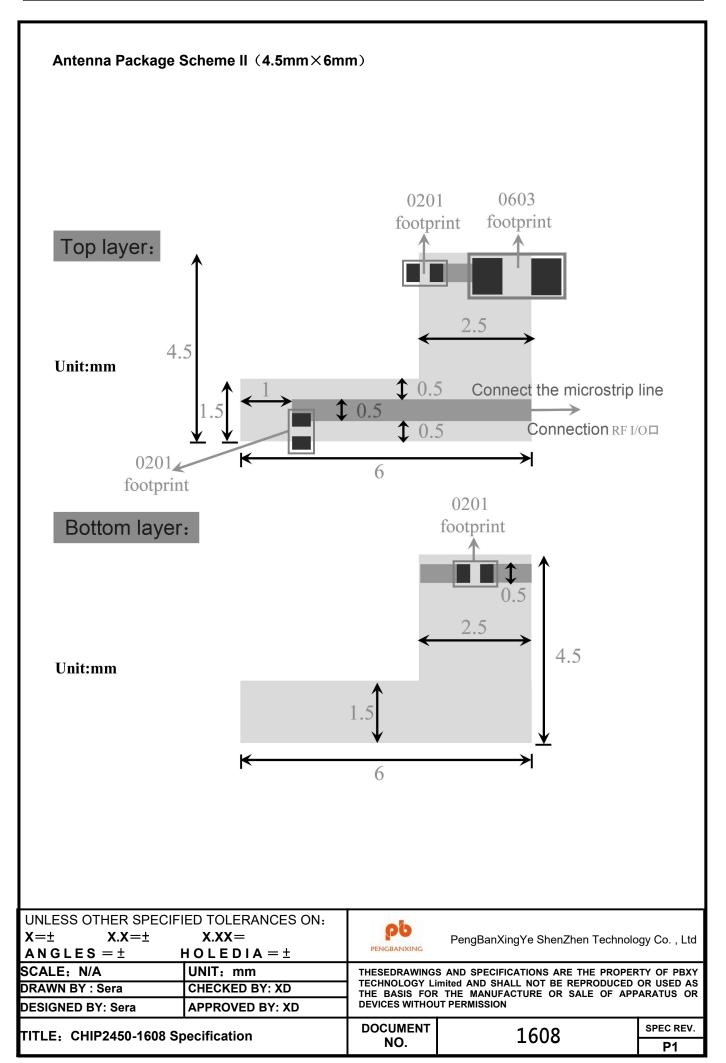
UNLESS OTHER SPECIF $X=\pm$ X.X=± ANGLES = ±	ED TOLERANCES ON: X.XX= HOLEDIA=±	PENGBANXING	PengBanXingYe ShenZhen Technolo	ogy Co. , Ltd	
SCALE: N/A	UNIT: mm	THESEDRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF PB		-	
DRAWN BY : Sera CHECKED BY: XD		TECHNOLOGY Limited AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR			
DESIGNED BY: Sera	APPROVED BY: XD	DEVICES WITHOUT PERMISSION			
TITLE: CHIP2450-1608 Specification		DOCUMENT	1608	SPEC REV.	
		NO.	1000	P1	

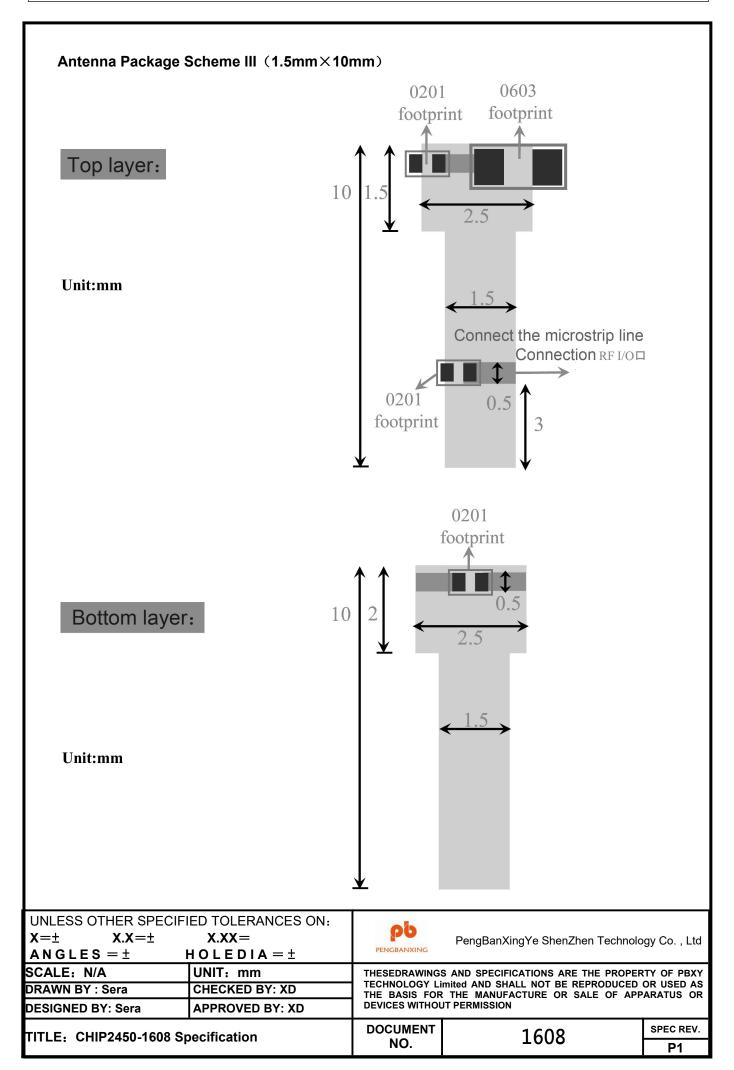


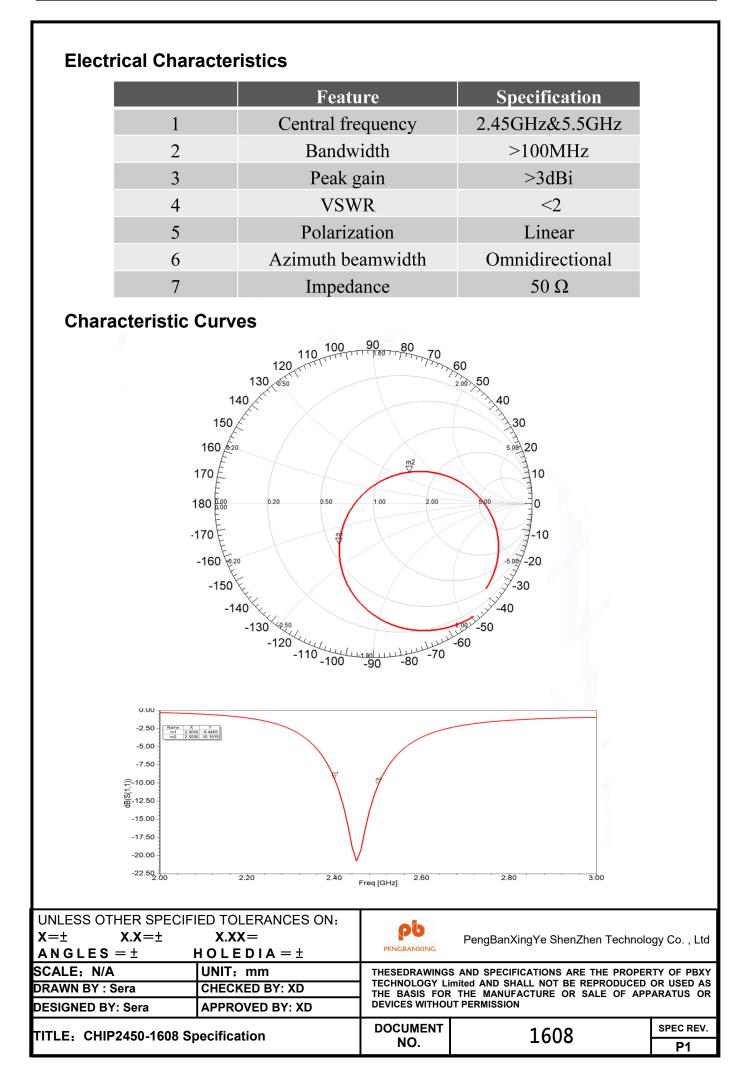
other PCBA circuit or material isolation.

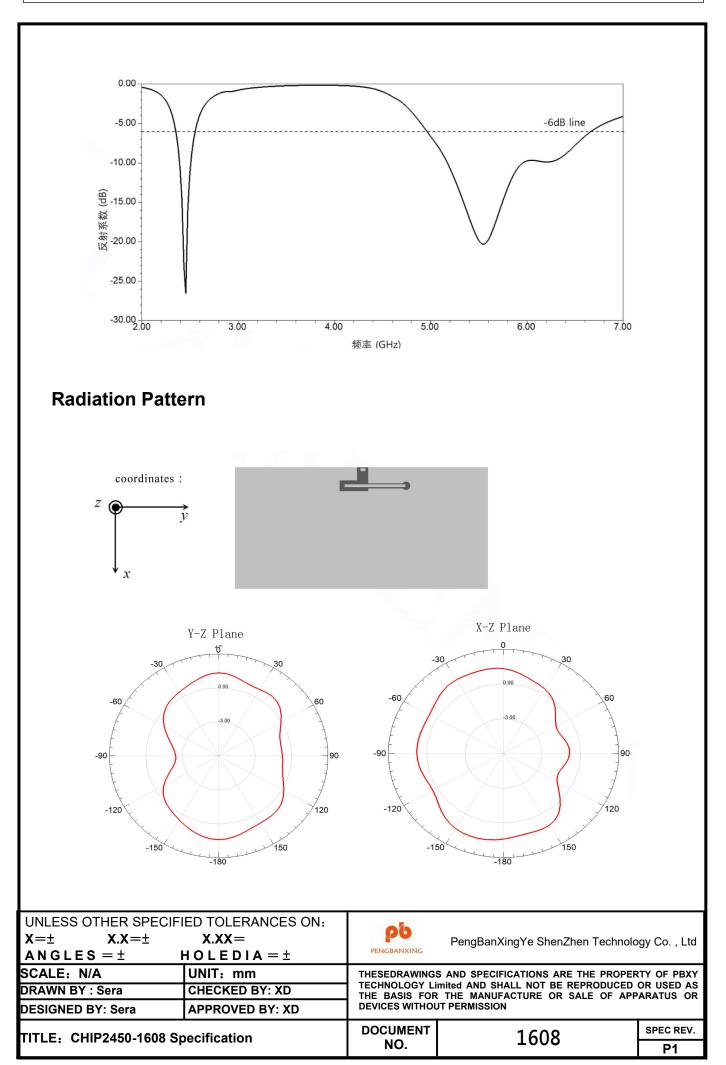
UNLESS OTHER SPECIF $X=\pm$ X.X= \pm ANGLES = \pm	IED TOLERANCES ON: X.XX= H O L E D I A = ±	PENGBANXING	PengBanXingYe ShenZhen Technolo	ogy Co. , Ltd
SCALE: N/A	UNIT: mm	THESEDRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF PE TECHNOLOGY Limited AND SHALL NOT BE REPRODUCED OR USED THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS		
DRAWN BY : Sera	CHECKED BY: XD			
DESIGNED BY: Sera	APPROVED BY: XD	DEVICES WITHOU	JT PERMISSION	-
TITLE: CHIP2450-1608 Specification DOCUMENT NO.			1608	SPEC REV.
		1008	P1	

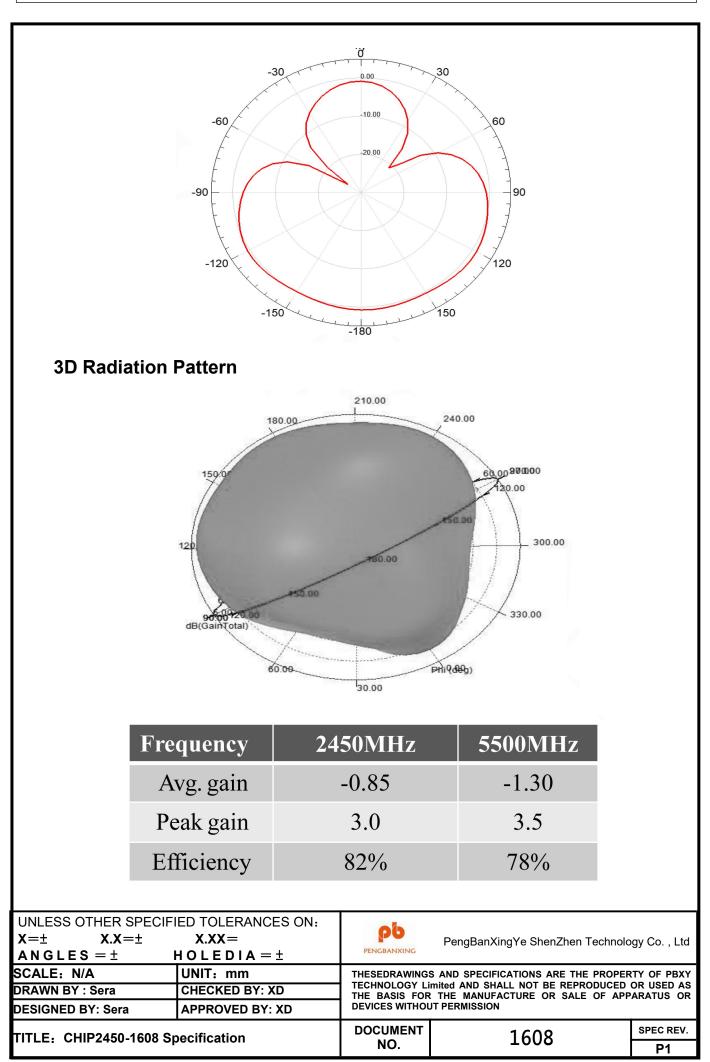






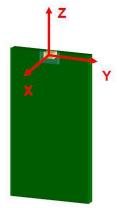


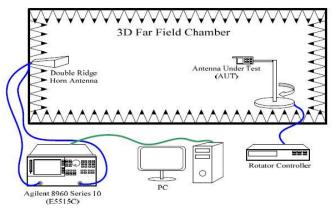




Radiation Pattern

The Gain pattern is measured in FAR-field chamber. DUT is placed on the table of rotator, a standard horn antenna and Vector Network Analyzer is used to collect data.





Environmental Characteristics

(1) Reliability Test

Item	Condition	Specification
Thermal shock	1. 30 ± 3 minutes at -40° C $\pm5^{\circ}$ C, 2. Convert to $\pm105^{\circ}$ C (5 minutes) 3. 30 ± 3 minutes at $\pm105^{\circ}$ C $\pm5^{\circ}$ C, 4. Convert to -40° C (5 minutes) 5. Total 100 continuous cycles	No apparent damage Fulfill the electrical spec. after test.
Humidity resistance	1. Humidity: 85% R.H. 2. Temperature: $85\pm5^{\circ}$ C 3. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
High temperature resistance	1. Temperature: 150°C±5°C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Low temperature resistance	1. Temperature: -40° C±5° C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Soldering heat resistance	1. Solder bath temperature : 260±5℃ 2. Bathing time: 10±1 seconds	No apparent damage
Solderability	The dipped surface of the terminal shall be at least 95% covered with solder after dipped in solder bath of 245 ± 5 °C for 3 ± 1 seconds.	No apparent damage

(2) Storage Condition

(a) At warehouse:

The temperature should be within $0 \sim 30^{\circ}$ C and humidity should be less than 60% RH.

The product should be used within 1 year from the time of delivery.

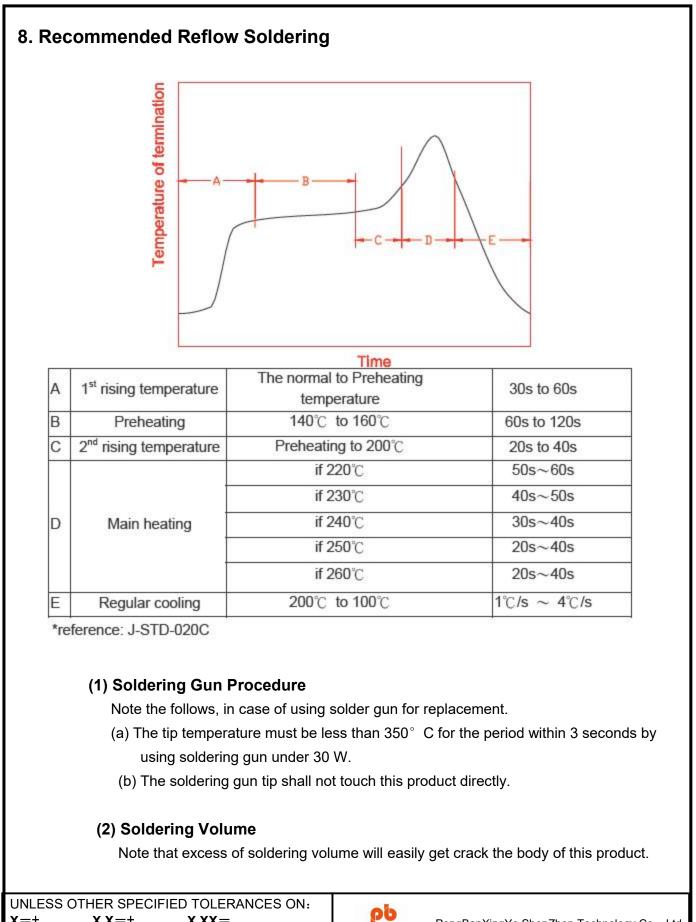
(b) On board:

The temperature should be within -40~85°C and humidity should be less than 85% RH.

(3) Operating Temperature Range

Operating temperature range : -40 $^\circ\!\mathrm{C}$ to +105 $^\circ\!\mathrm{C}$.

UNLESS OTHER SPECIFI $X=\pm$ $X.X=\pm$ $A N G L E S = \pm$	ED TOLERANCES ON: X.XX= HOLEDIA=±	PENGBANXING	PengBanXingYe ShenZhen Technolo	gy Co. , Ltd
SCALE: N/A DRAWN BY : Sera	UNIT: mm CHECKED BY: XD	THESEDRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF PE TECHNOLOGY Limited AND SHALL NOT BE REPRODUCED OR USED		-
DRAWN BT : Sera		THE BASIS FOR	THE MANUFACTURE OR SALE OF APP	ARATUS OR
DESIGNED BY: Sera	APPROVED BY: XD	DEVICES WITHOUT PERMISSION		
TITLE: CHIP2450-1608 Specification		DOCUMENT	1608	SPEC REV.
TTEL: 0111 2450-1000 5	becincation	NO. 1000		P1



<u>A-1</u> <u>A.A-1</u>	A.AA-		PengBanXingYe ShenZhen Technol	ogy Co. , Ltd	
$ANGLES = \pm$	$HOLEDIA = \pm$	PENGBANXING			
SCALE: N/A	UNIT: mm	THESEDRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF PBX TECHNOLOGY Limited AND SHALL NOT BE REPRODUCED OR USED A THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS O DEVICES WITHOUT PERMISSION			
DRAWN BY : Sera	CHECKED BY: XD				
DESIGNED BY: Sera	APPROVED BY: XD				
TITLE: CHIP2450-1608 Specification		DOCUMENT	1608	SPEC REV.	
		NO.	1000	P1	

